

U.S. Department of Commerce, Patent and Trademark Office					Atty Docket No.		Serial No.	
					M-7125-2D US		Unknown	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT					Applicant(s)			
(Use several sheets if necessary)					Mayer, OSteven T., Bhaskaran, Vijay;			
					Filing Date		Group	
					Herewith		Unknown	
U.S. Patent Documents								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
W	AA	4,092,226	5/30/78	Laing et al.	204	51		
W	AB	5,618,634	4/8/97	Hosoda et al.	428	610		
W	AC	5,935,762	8/10/99	Dai et al.	430	312		
W	AD	5,936,707	8/10/99	Nguyen et al.	355	18		
W	AE	5,939,788	8/17/99	McTeer	257	751		
W	AF	5,972,192	10/26/99	Dubin et al.	205	101		
W	AG	6,099,711	8/8/00	Dahms et al.	205	101		
	AH							
	AI							
	AJ							
	AK							
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
	AL							
	AM							
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
W	AN	<u>ULSI Technology</u> , Eds, C.Y. Chang and S.M. Sze (McGraw-Hill, 1996, pp. 444-445).						
W	AO	<u>Electroplating</u> , Fredereick A. Lowenheim, , (McGraw-Hill, 1978, p 423).						
W	AP	<u>Selective and Blanket Electroless Cu Plating Initiated by Contact Displacement...</u> , Valery M. Dubin, Yosi Shacham-Diamand and Bin Zhao, P.K. Vasudev, Chiu H. Ting, (VMIC Conf. June 26 & 27, 1995, pp 314-321).						
W	AQ	<u>Copper Electroplating Process for Sub-Half-Micron ULSI Structures</u> , Robert J. Contolini, Lisa Tarte, Robert T. Graff, Lee B. Evans, J. Neal Cox, Marc R. Puich, Justin E. Gee, Xiao-Chun Mu, Chien Chiang, (VMIC Conf. June 27-29, 1995, pp. 322-325)						
Examiner William Leader			Date Considered 12/2001					
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.								

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